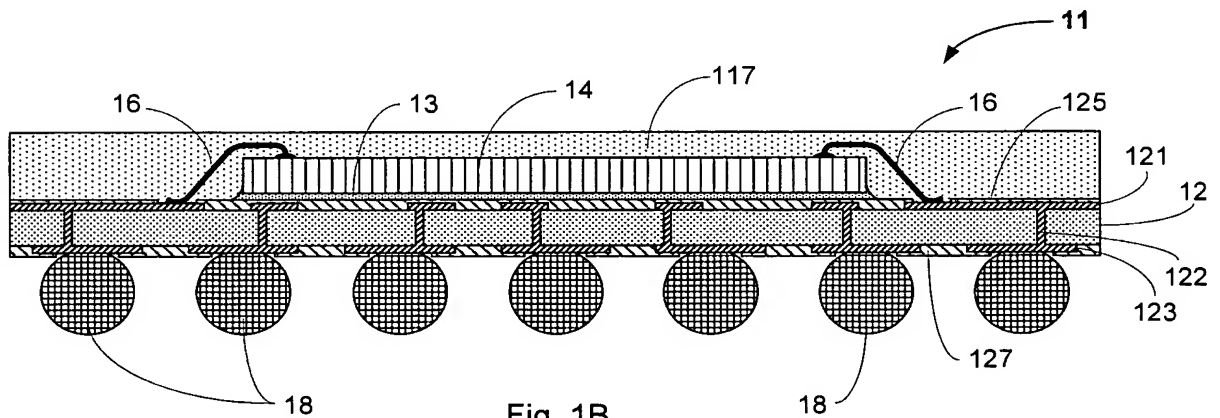
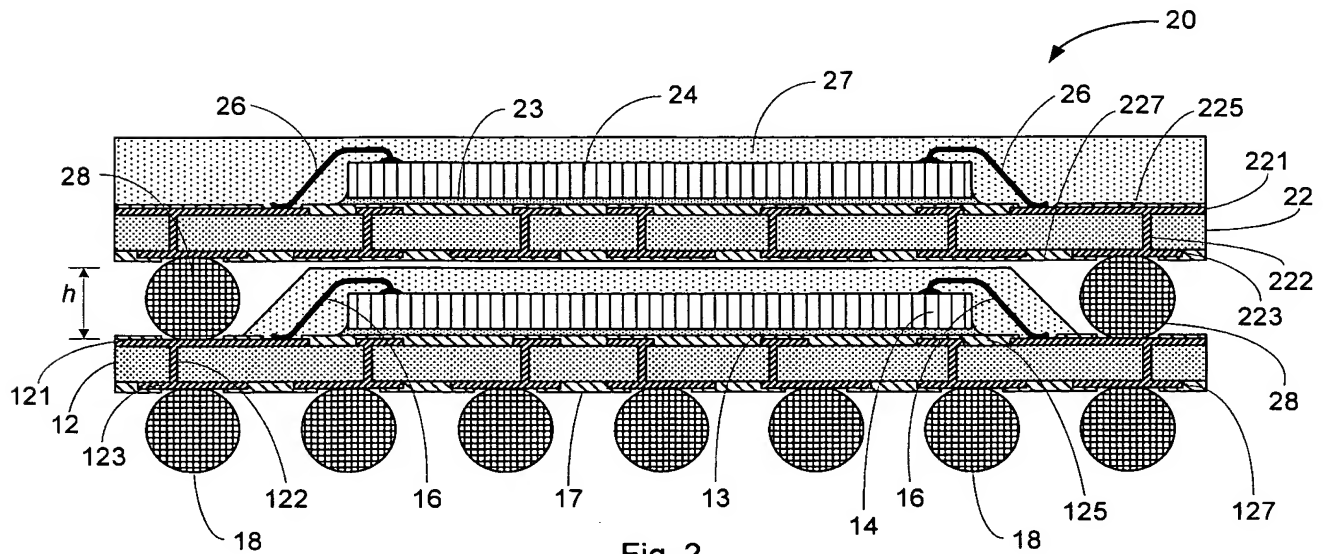
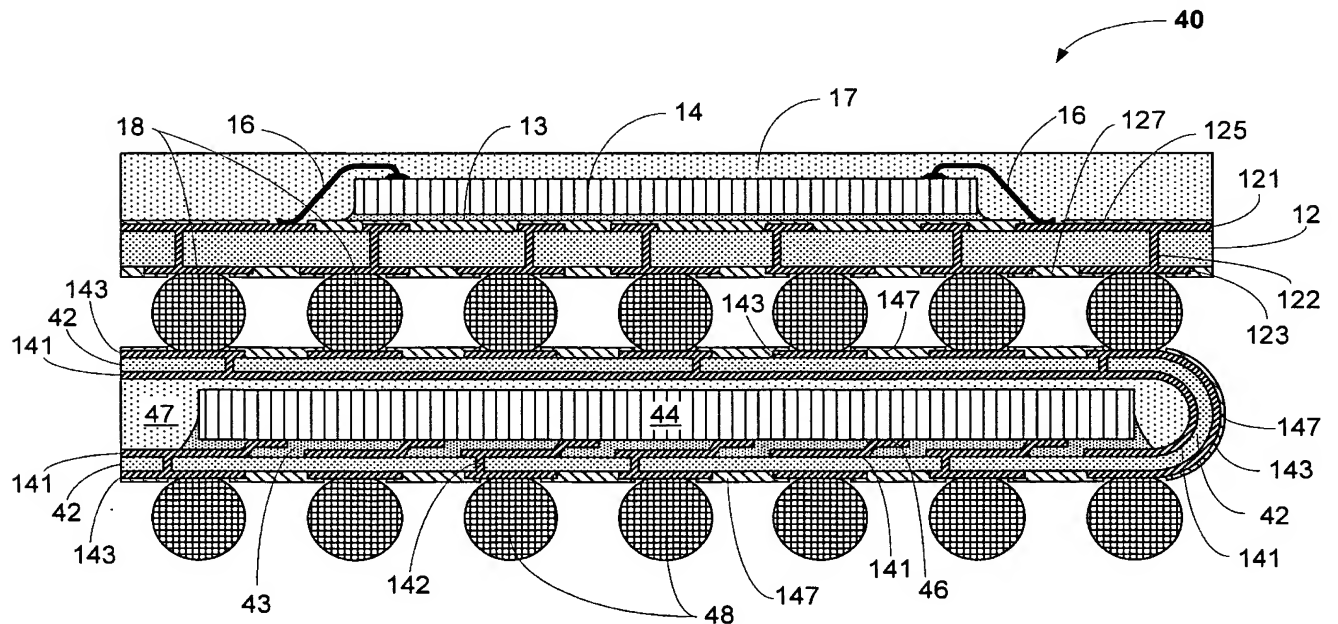
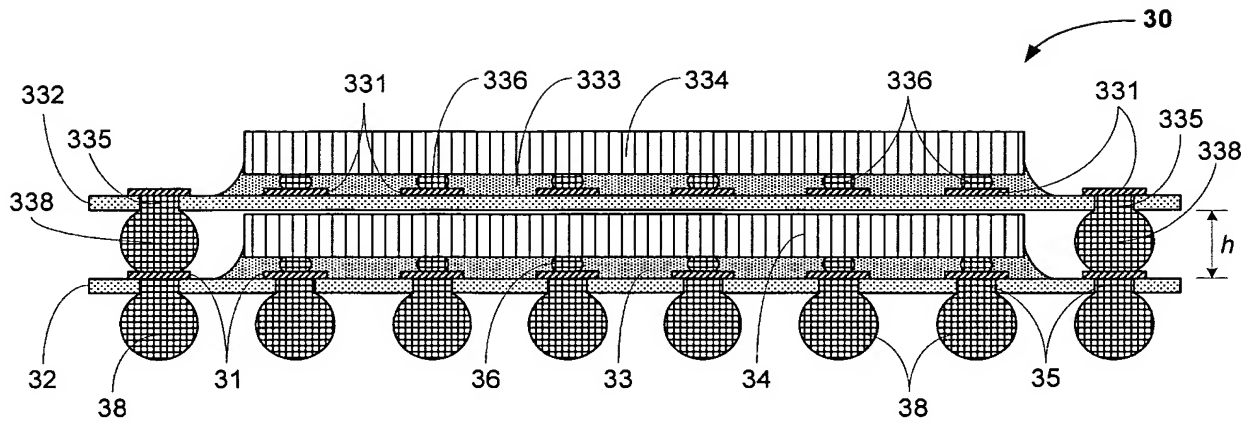
Fig. 1A  
PRIOR ARTFig. 1B  
PRIOR ARTFig. 2  
PRIOR ART



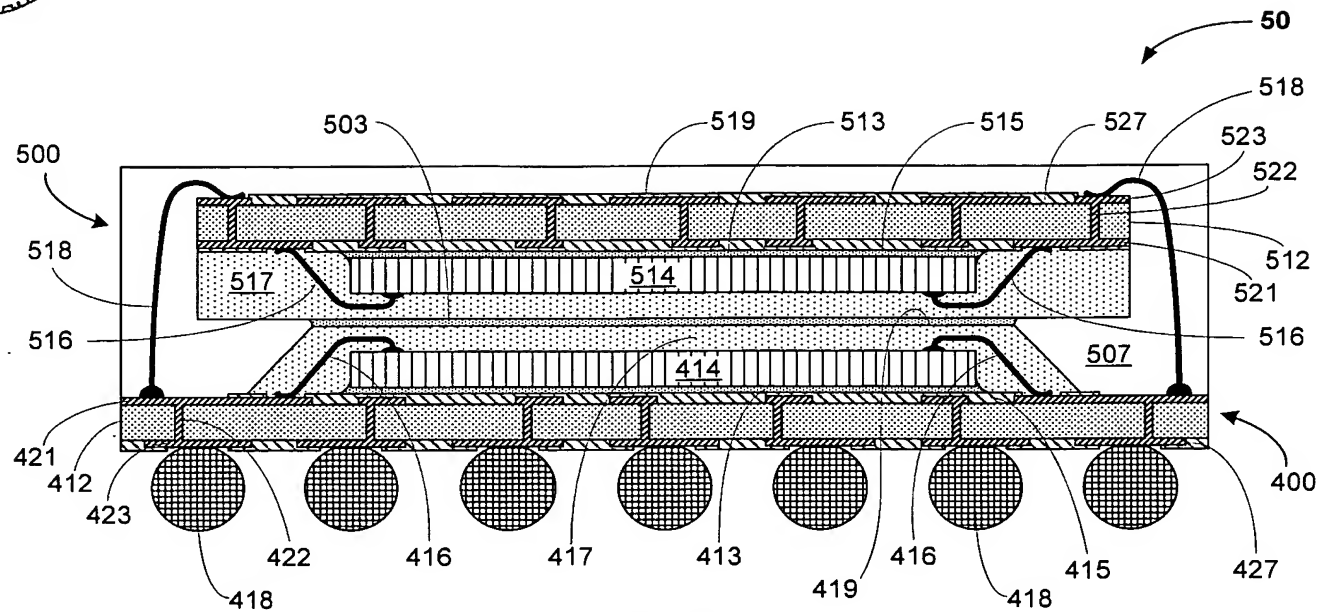


Fig. 5A

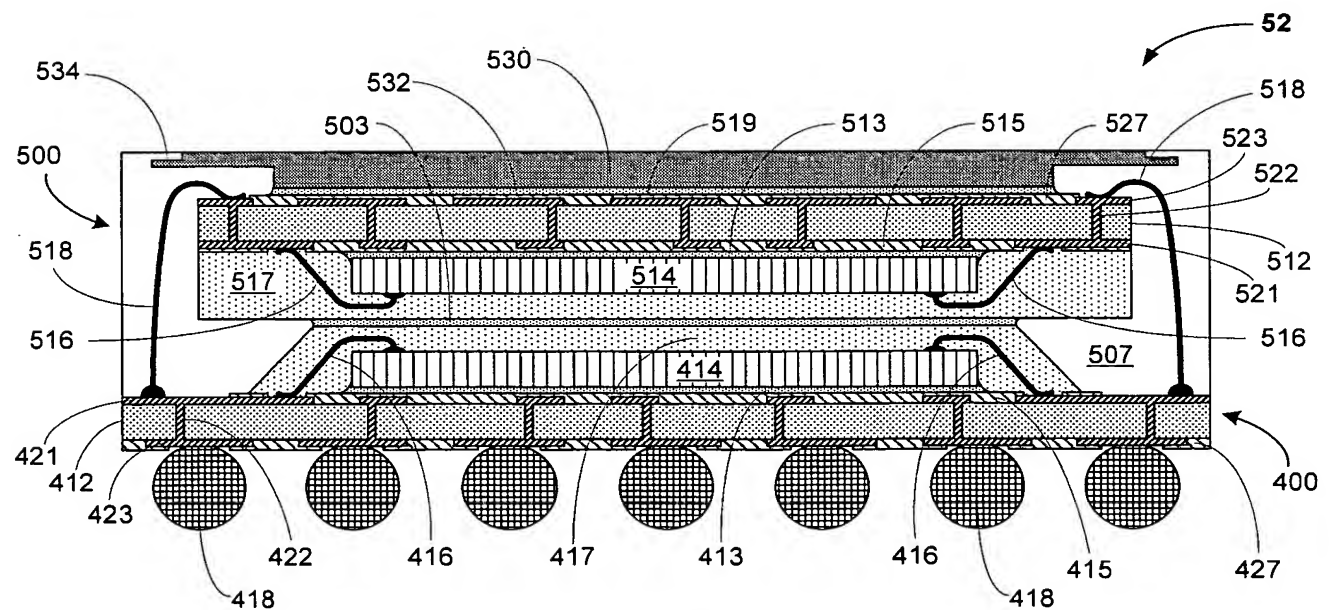


Fig. 5D

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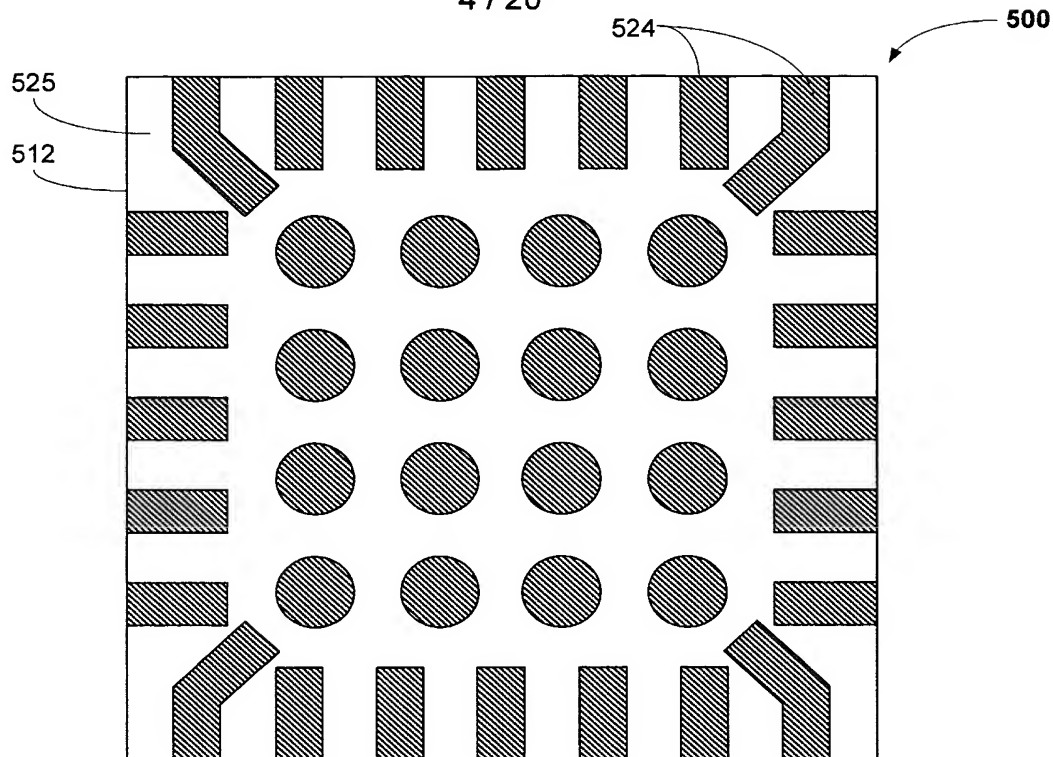


Fig. 5C

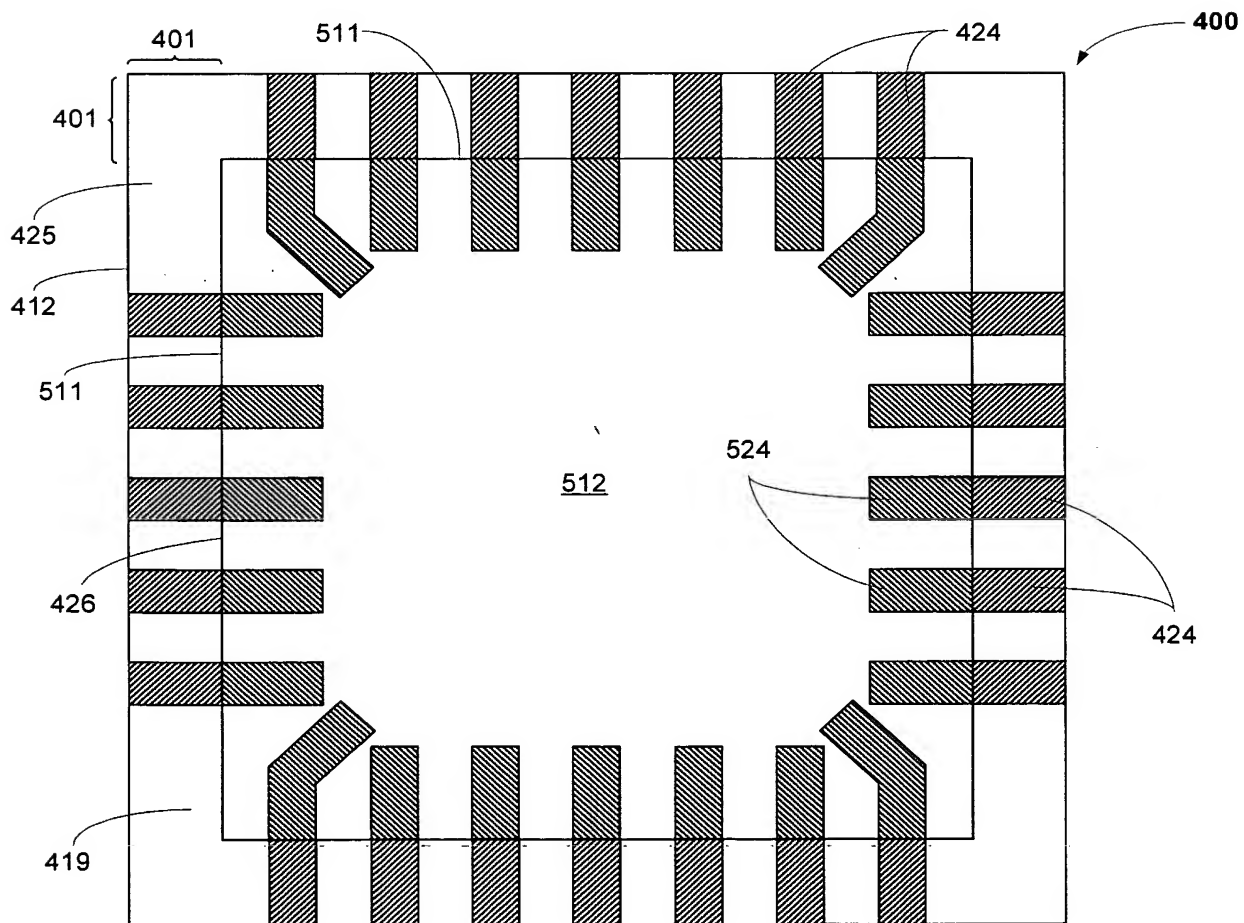


Fig. 5B

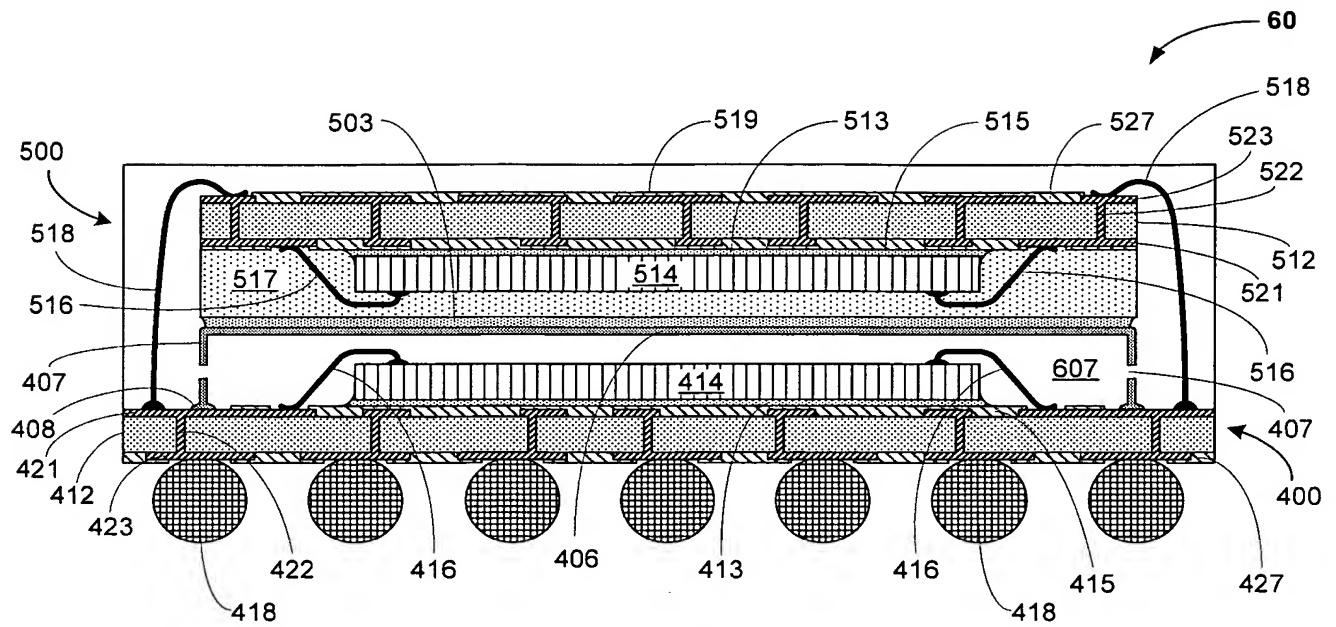
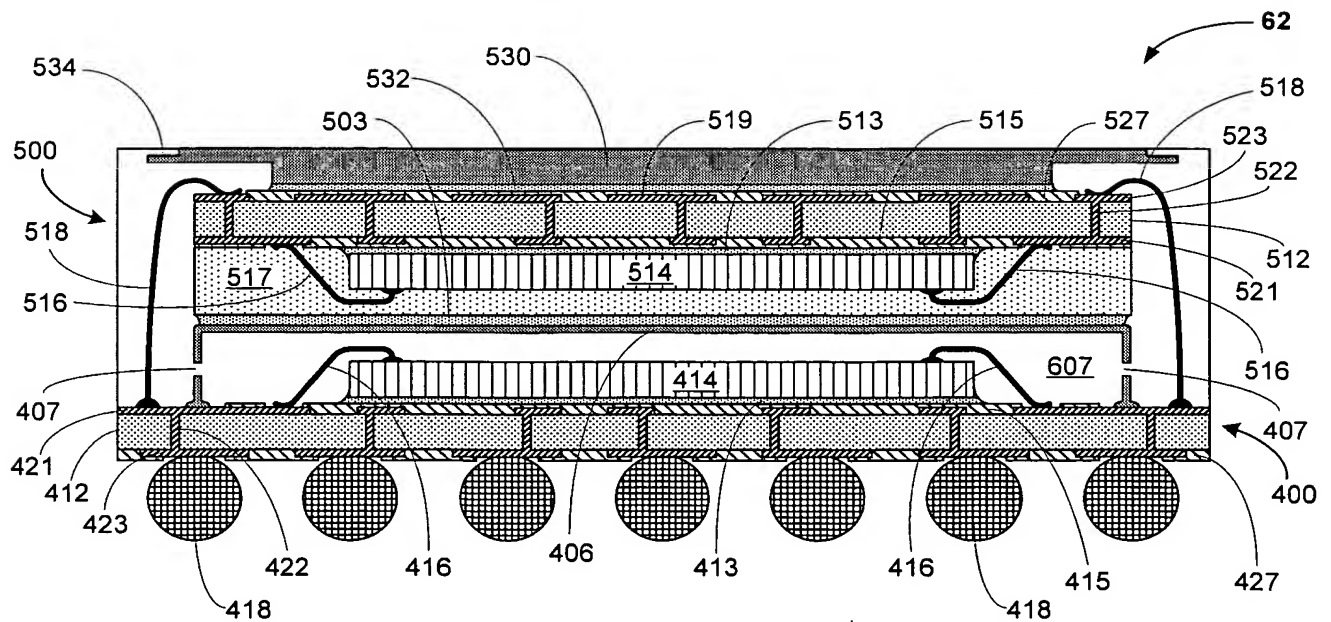


Fig. 6A



**Fig. 6B**

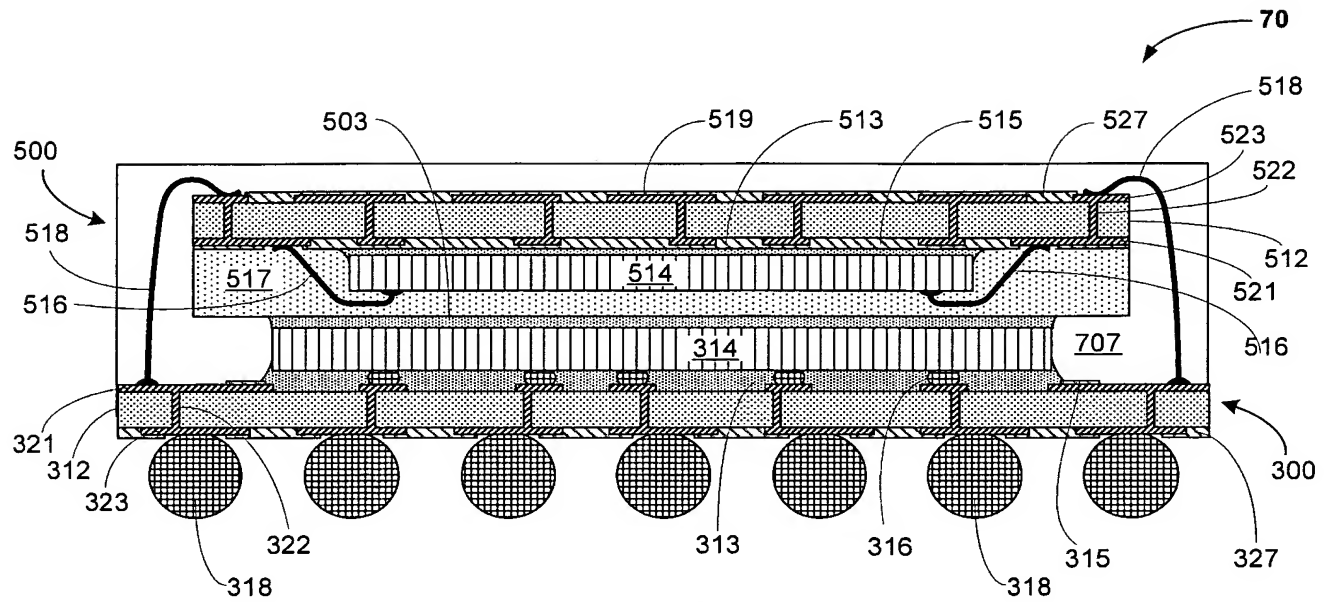


Fig. 7A

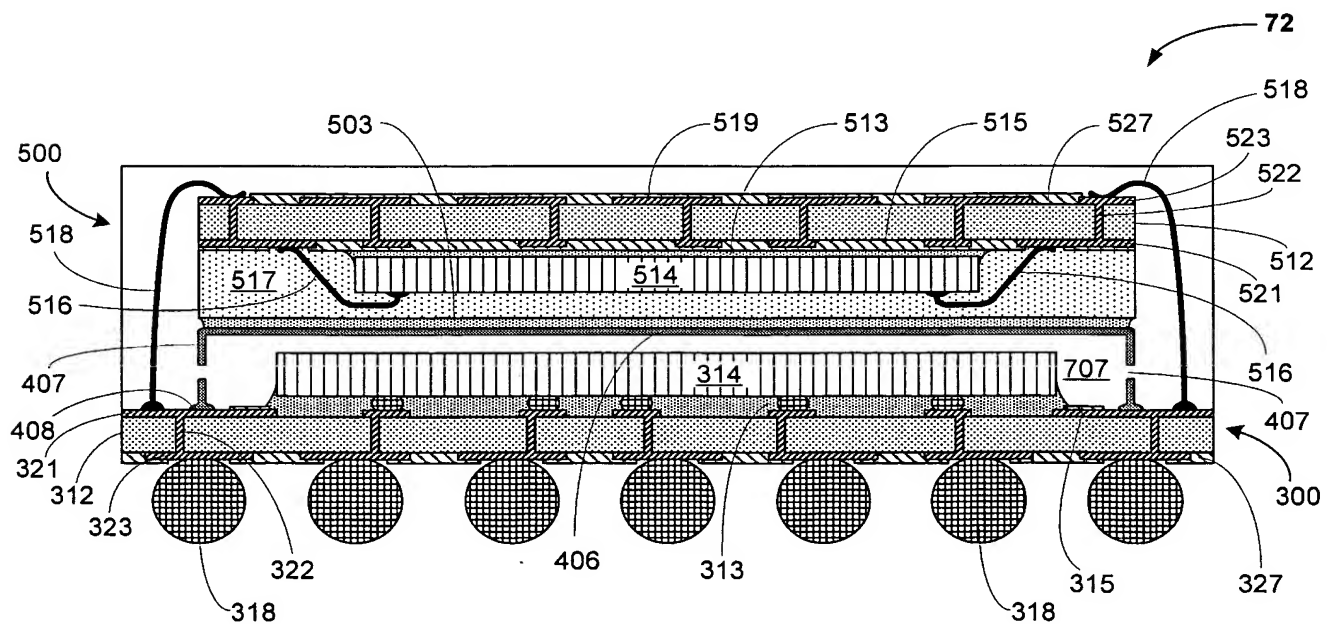


Fig. 7B

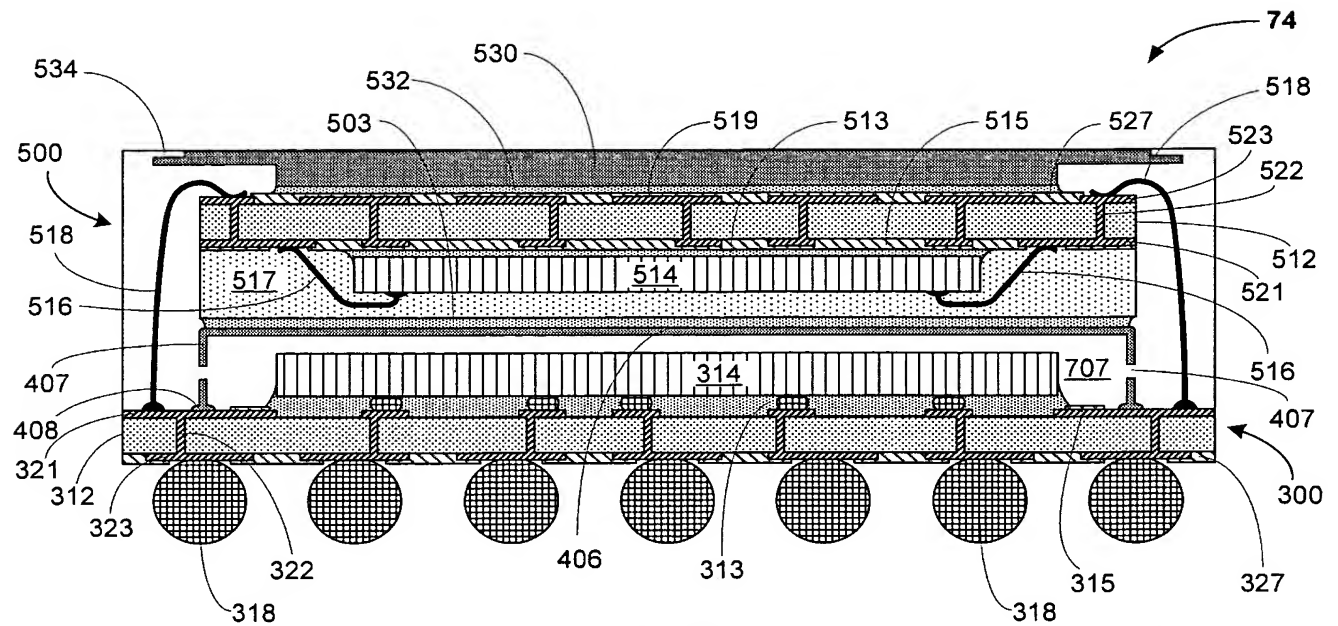


Fig. 7C

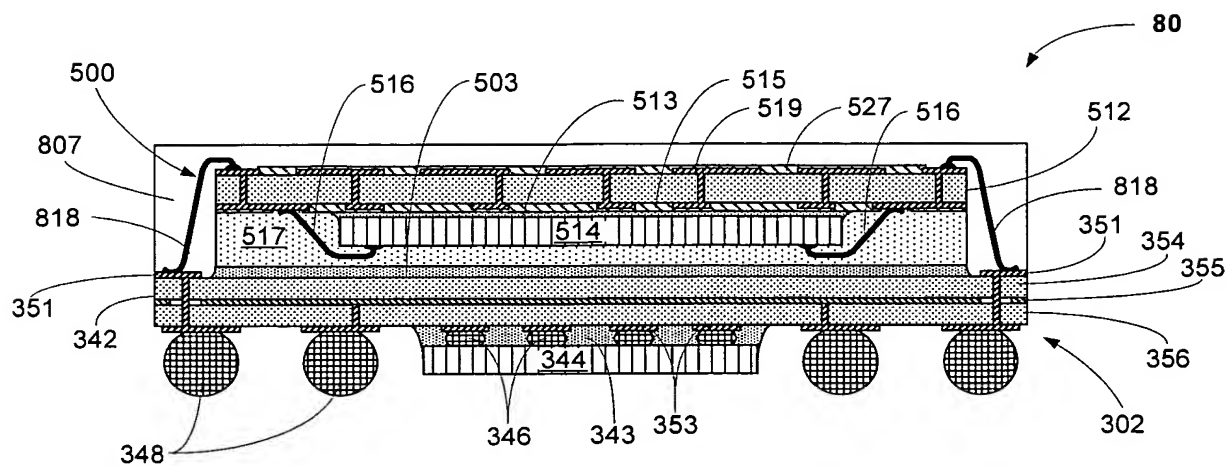


Fig. 8A

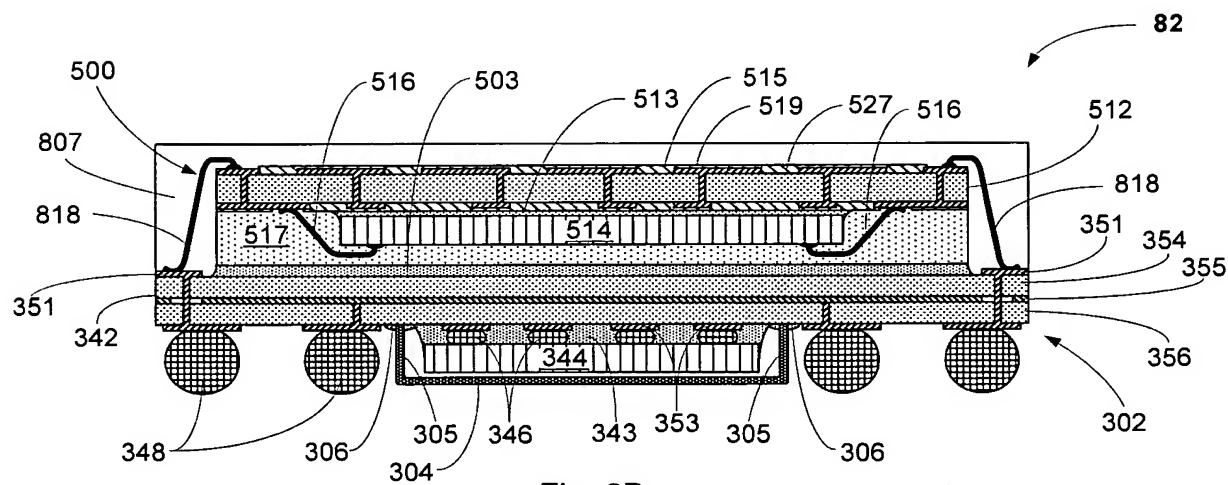


Fig. 8B

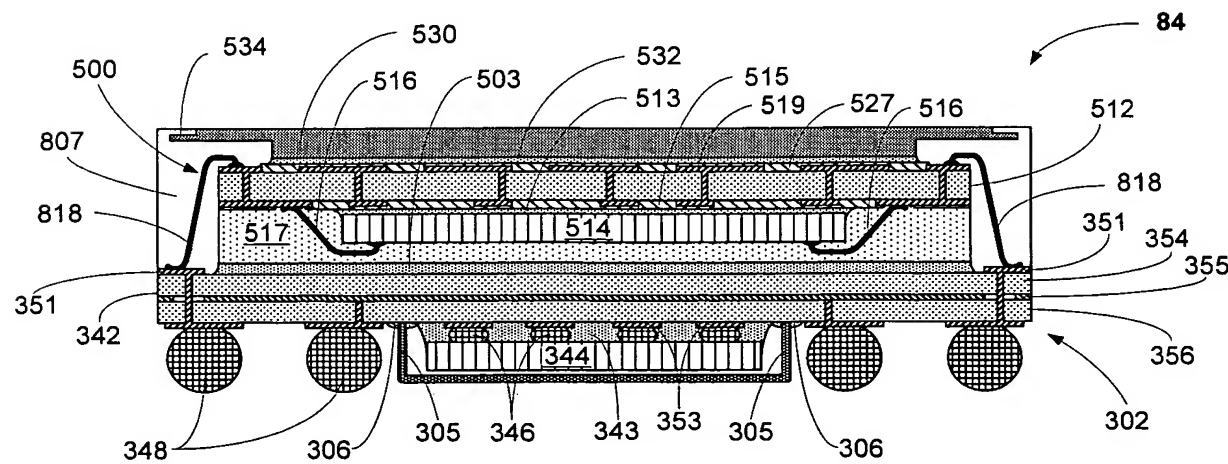
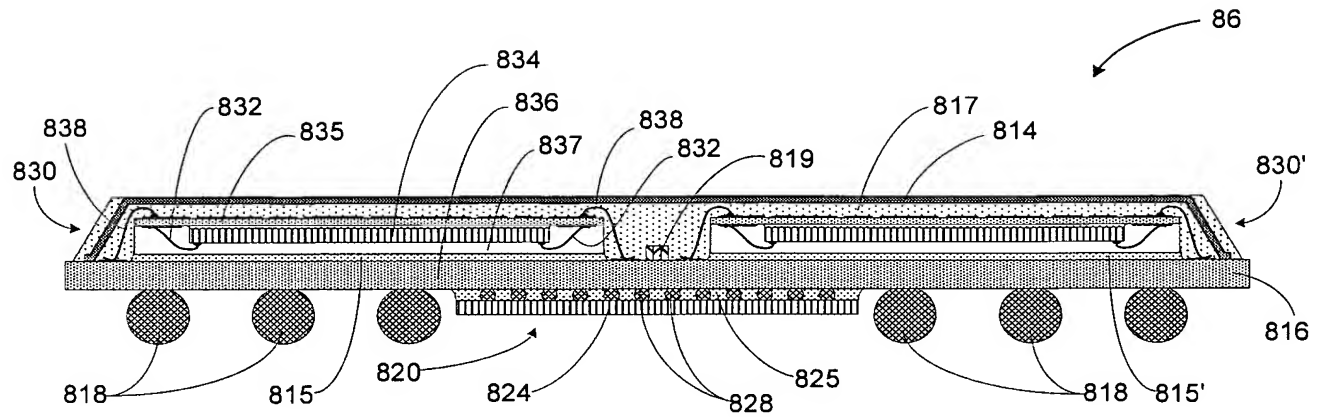
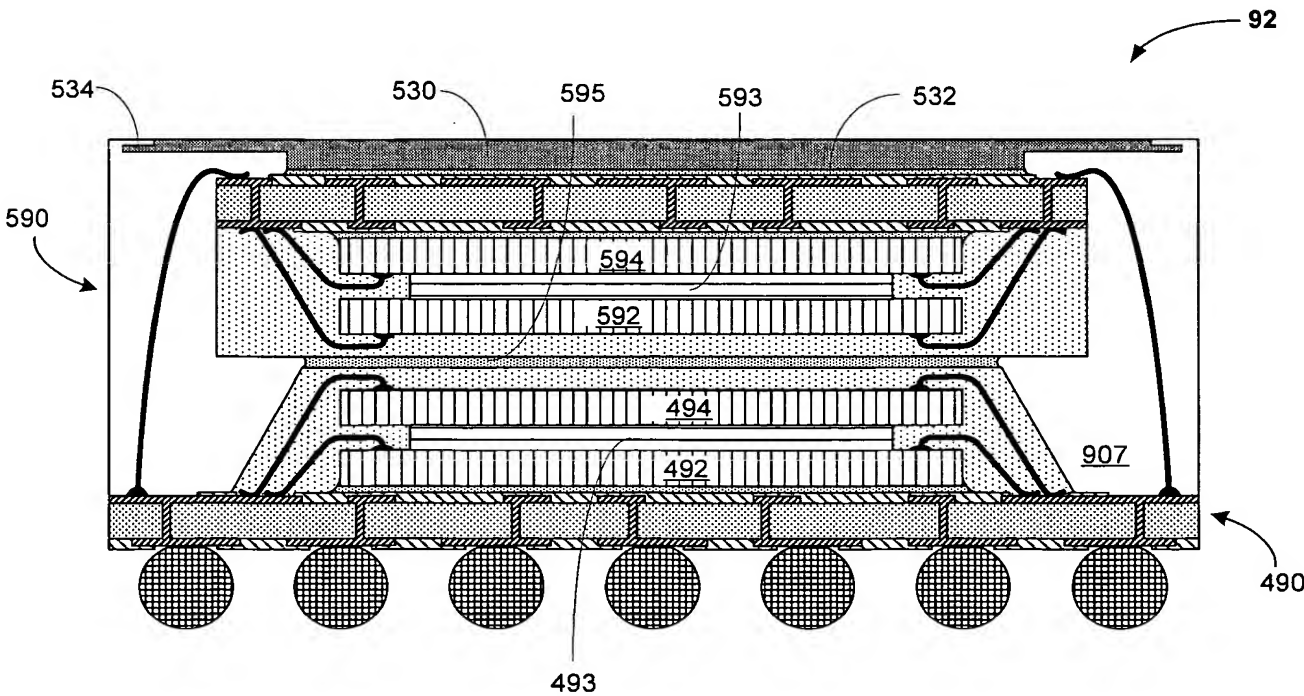
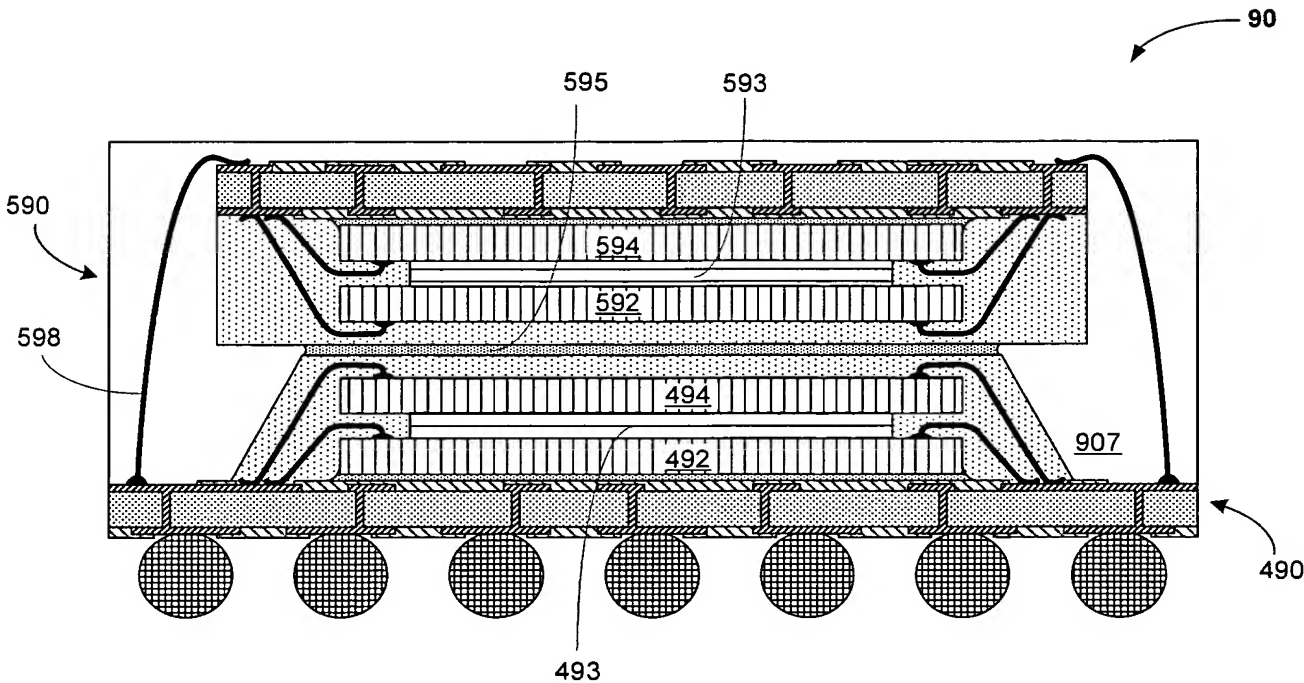
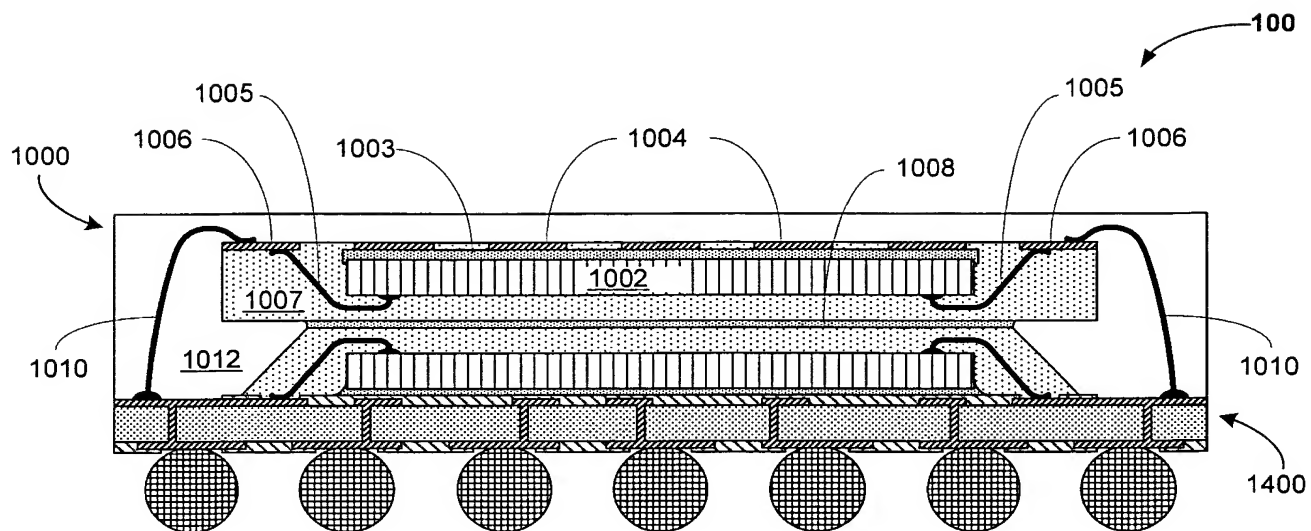


Fig. 8C









A detailed cross-sectional view of a multi-layered device assembly 1000. The assembly is built upon a base 1400, which is supported by a series of circular pillars 1010. A layer 1012 is positioned above the base. Above this is a layer 1020 containing two horizontal strips, 1002 and 1022. These strips are flanked by angled, textured regions 1003 and 1004. A top layer 1005 is shown with a wavy profile 1006. On the right side, a vertical textured region 1007 is labeled. Various other components are indicated by labels 1021, 1025, and 1026.

**Fig. 10B**

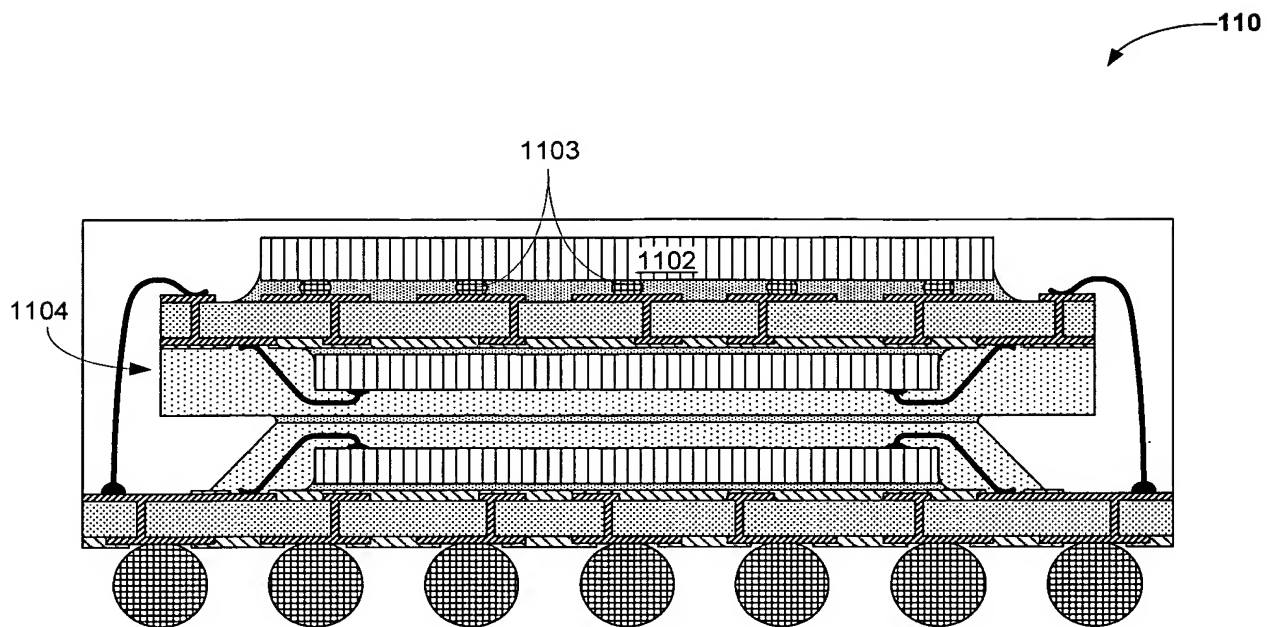


Fig. 11A

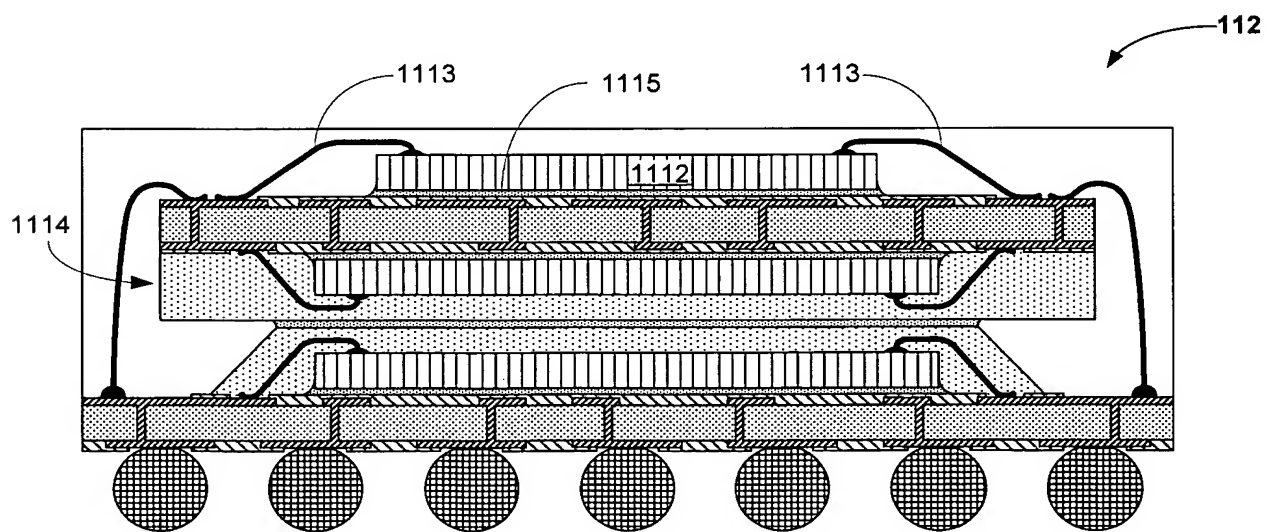


Fig. 11B

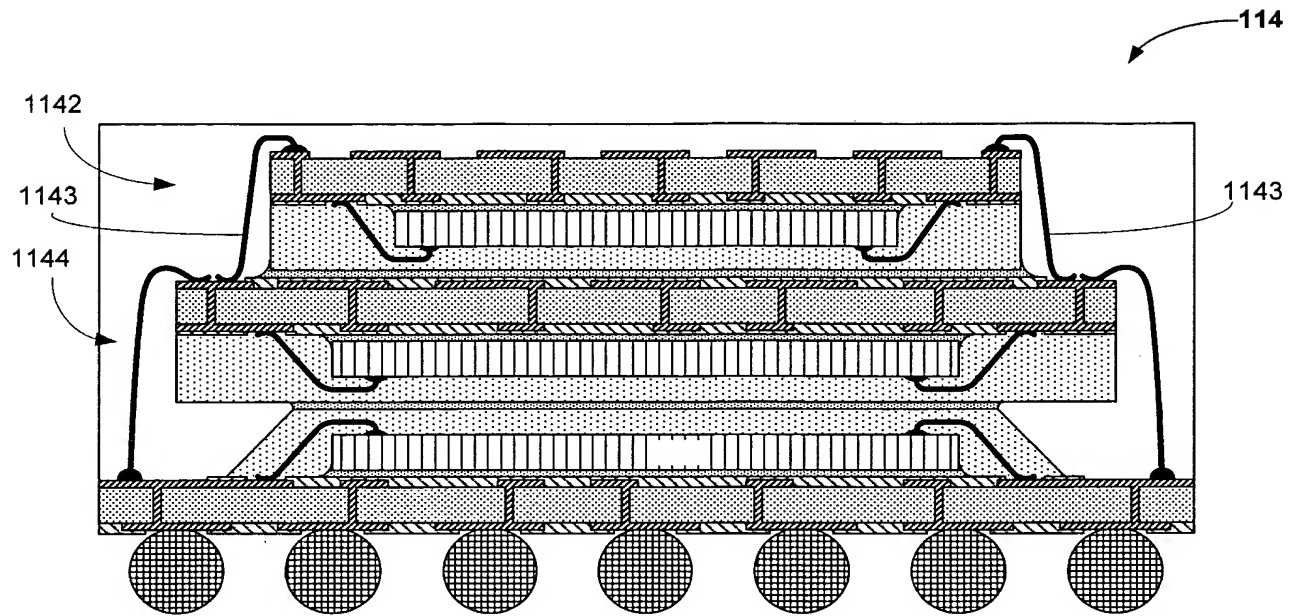


Fig. 11C

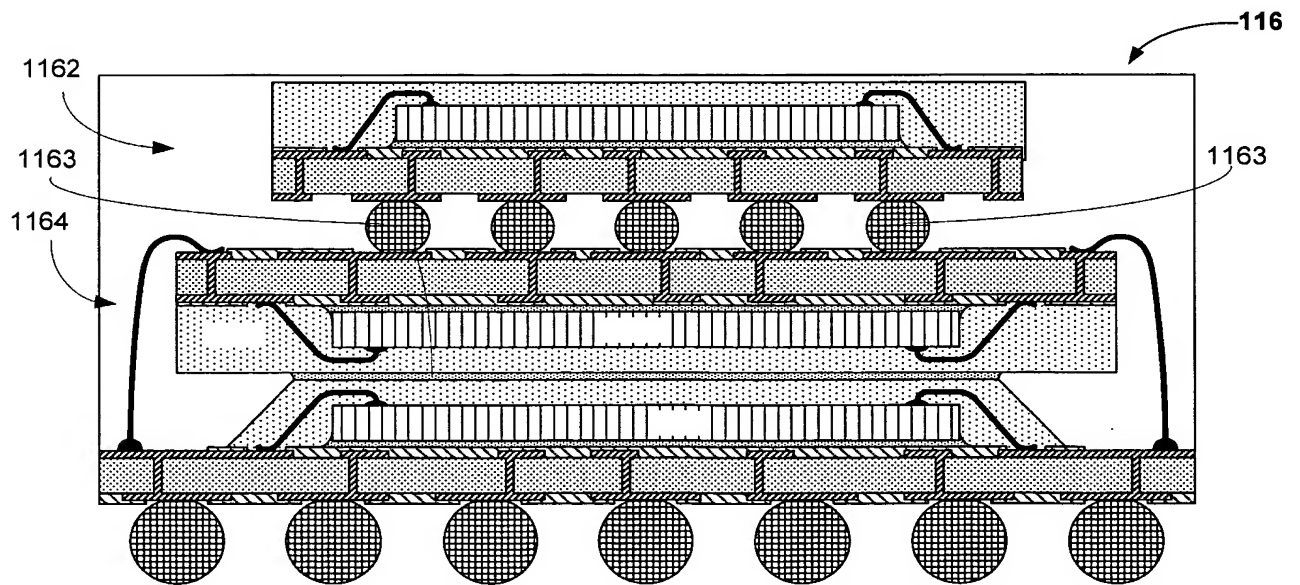


Fig. 11D

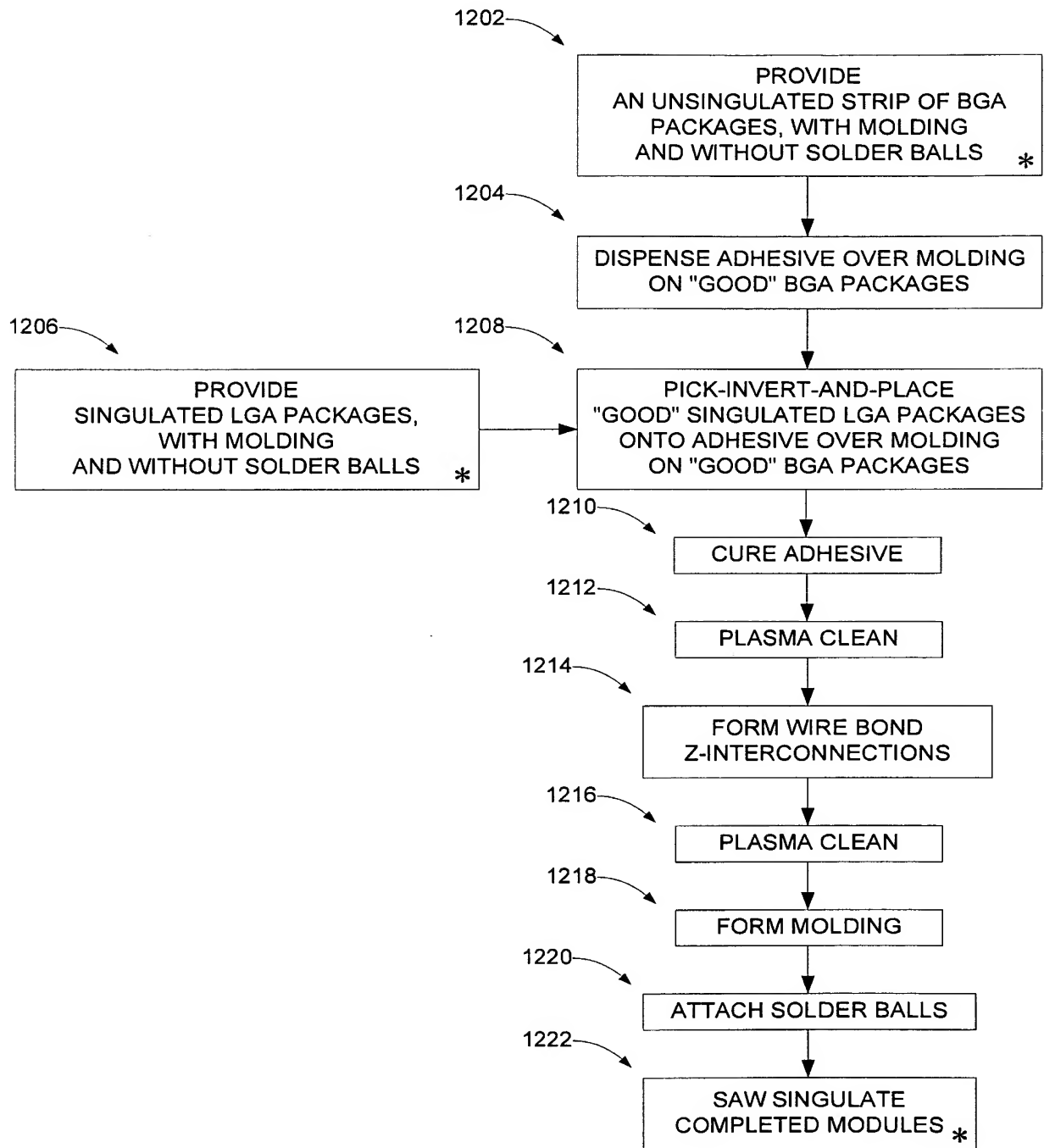


Fig. 12

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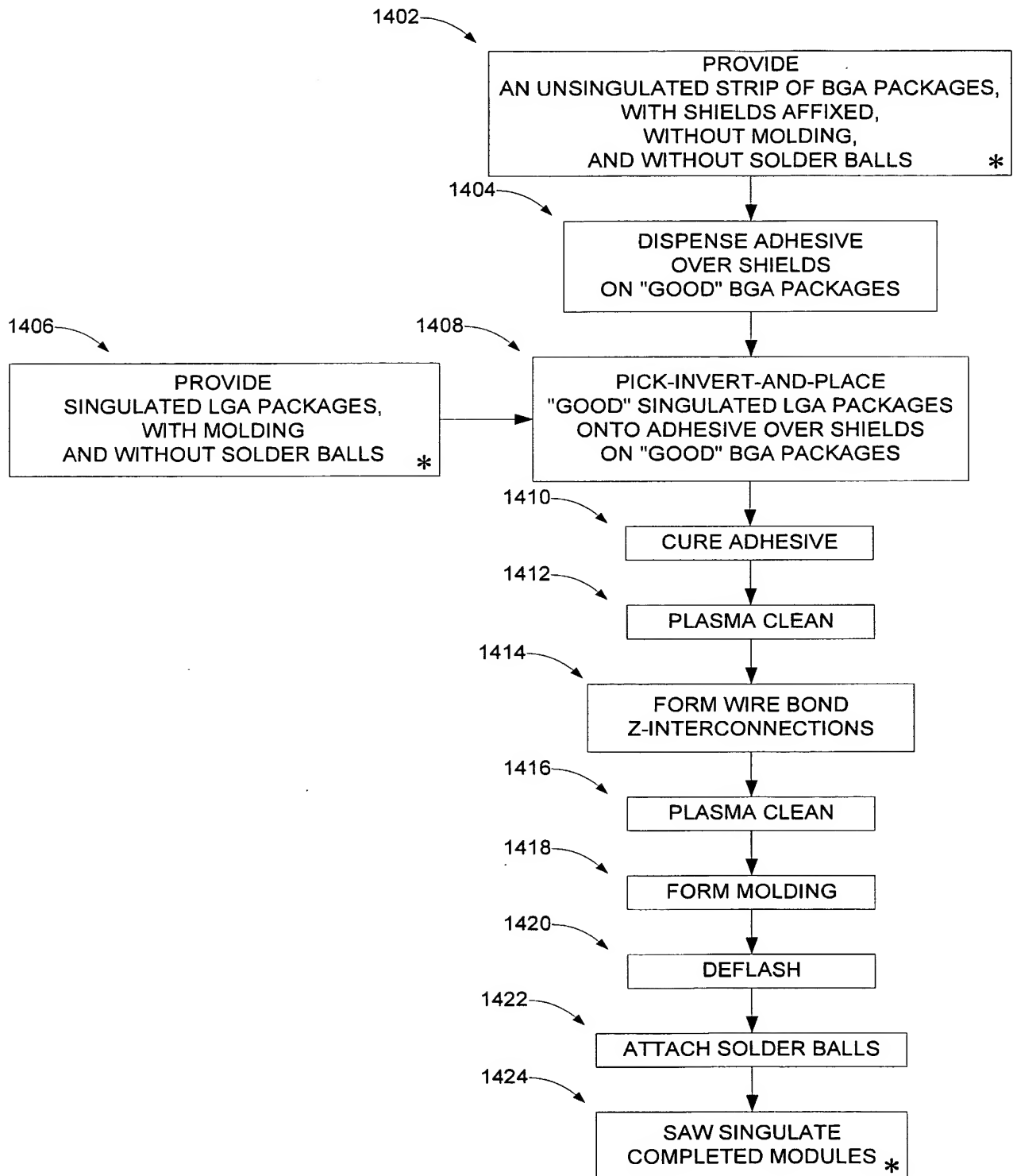


Fig. 13

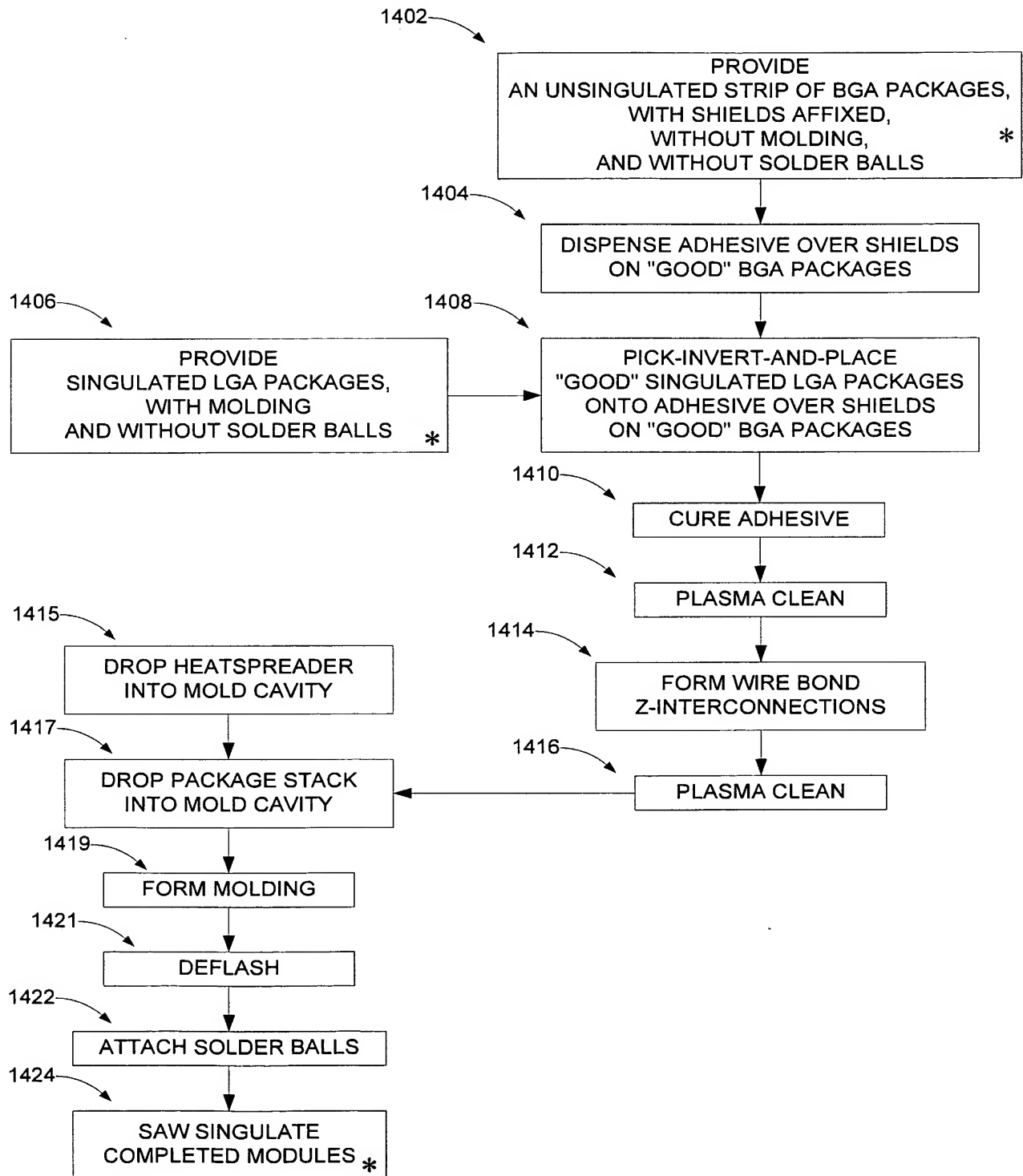


Fig. 14



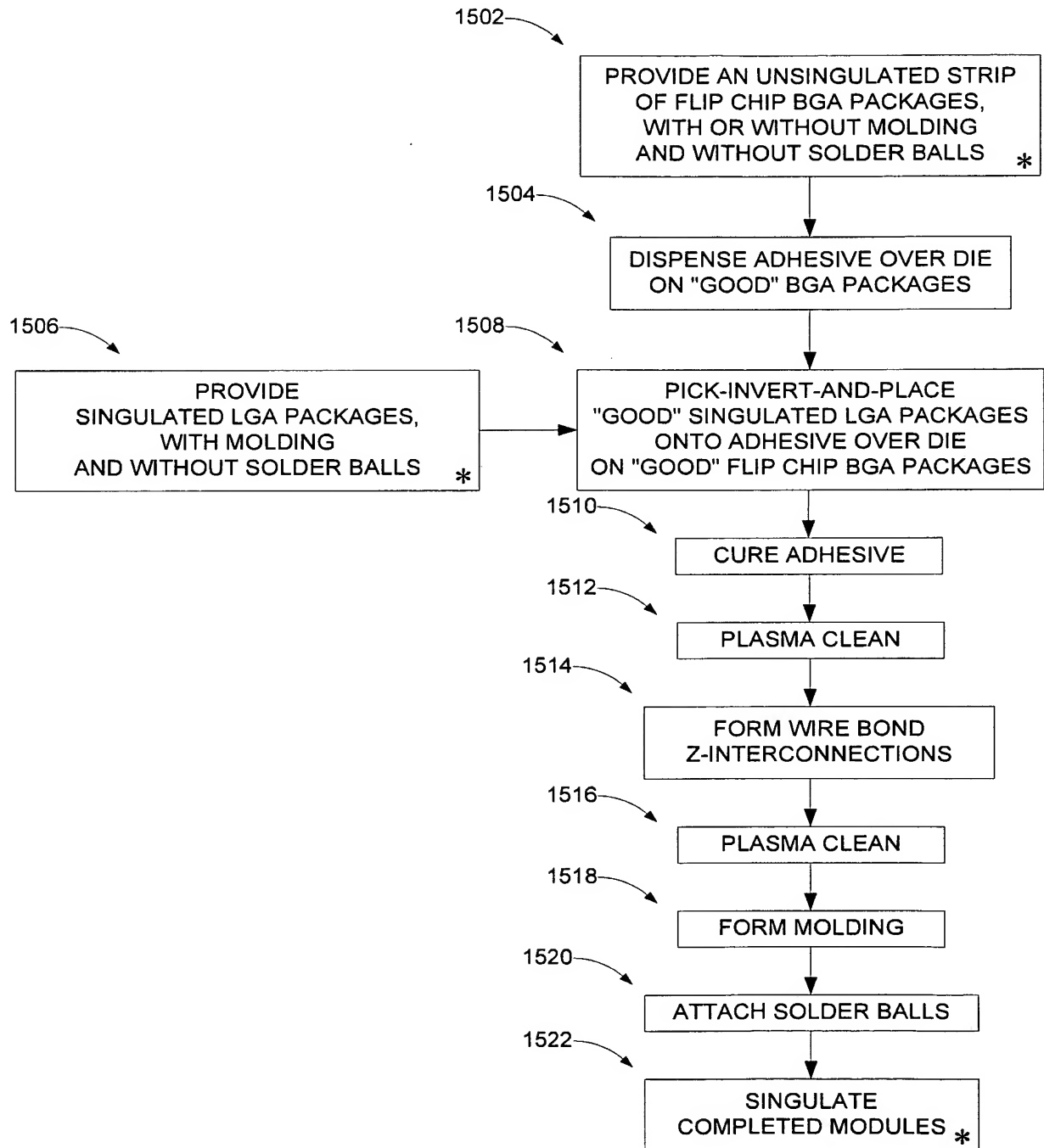


Fig. 15

## Replacement Sheet

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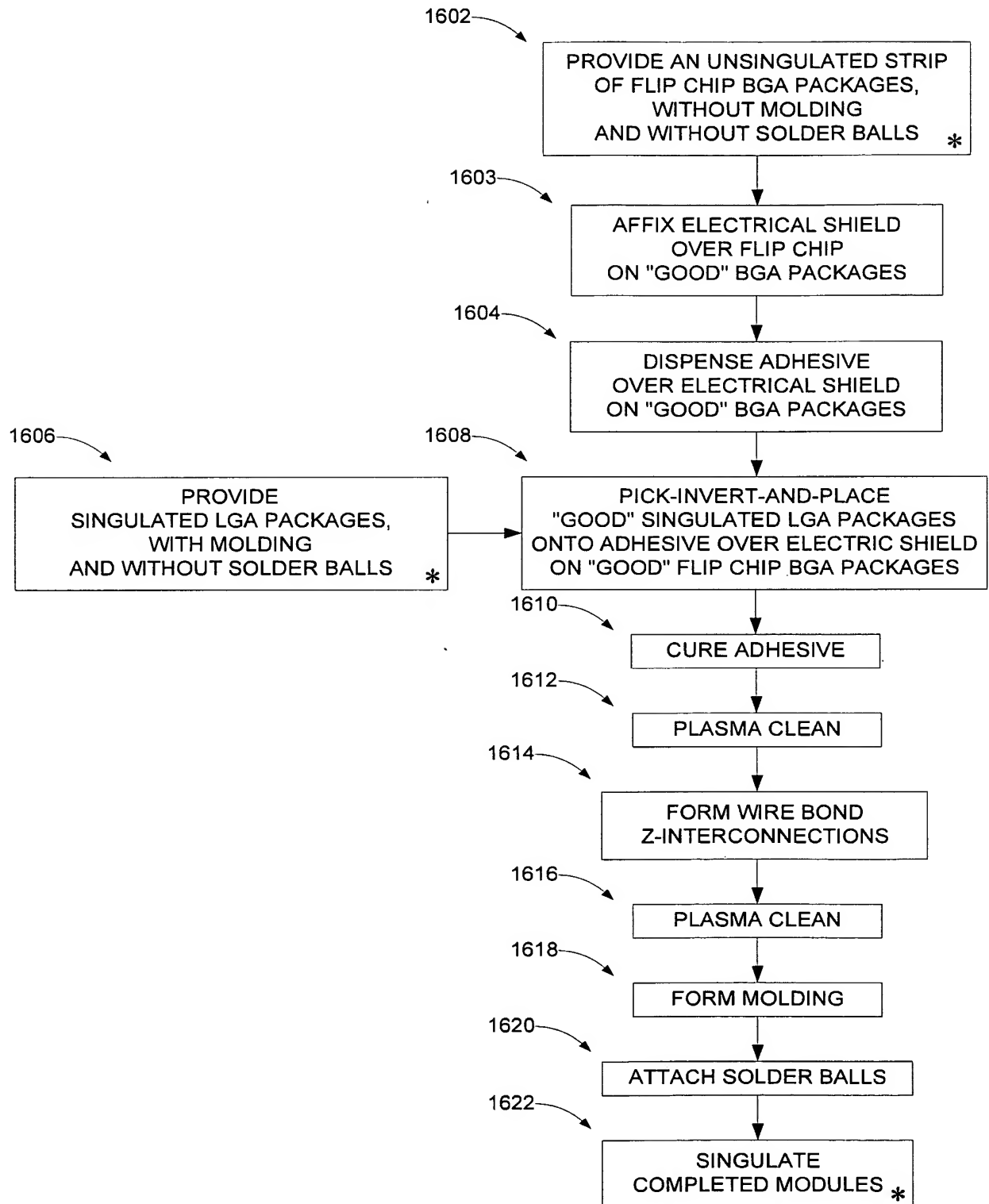


Fig. 16

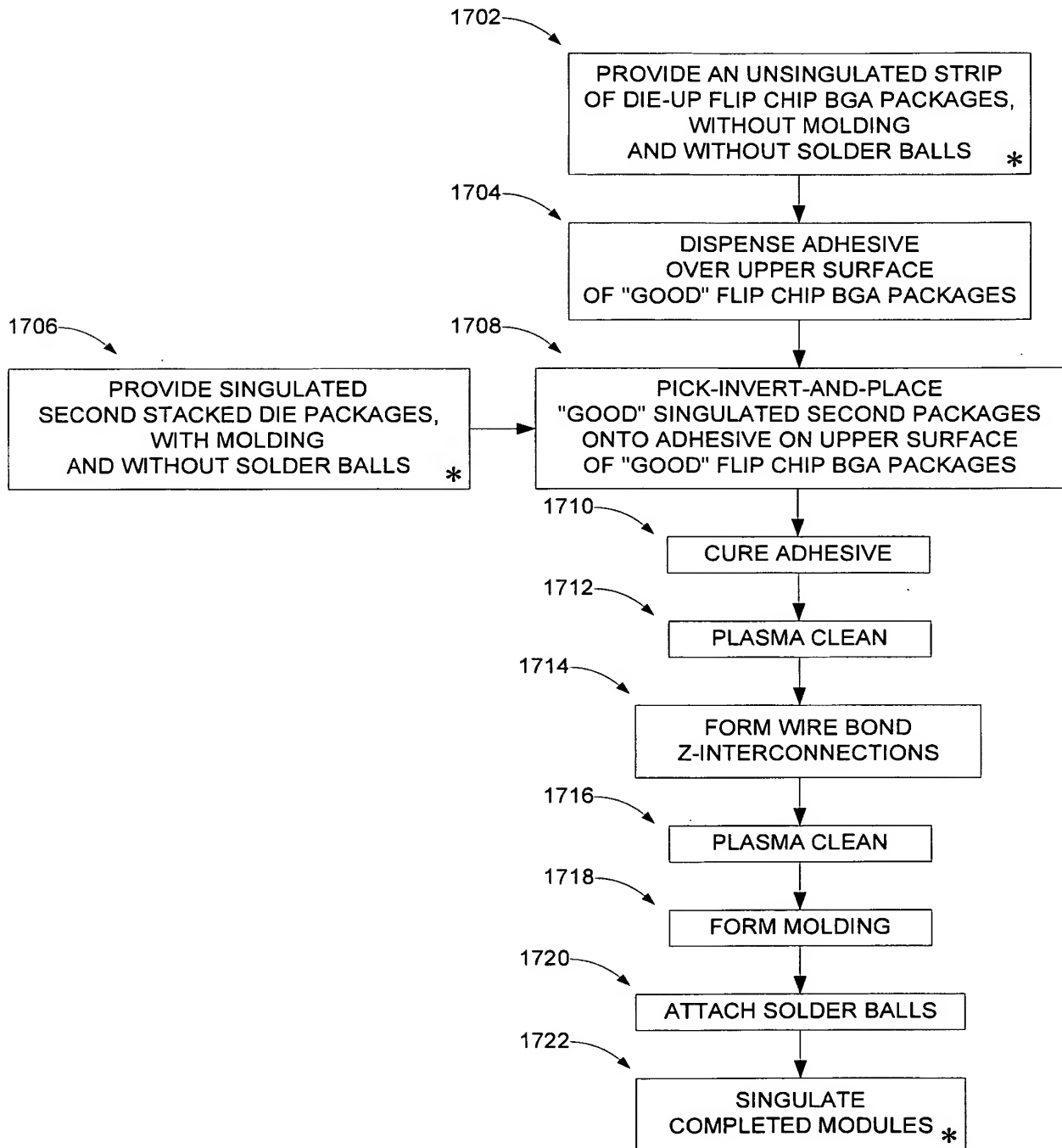


Fig. 17

Replacement Sheet

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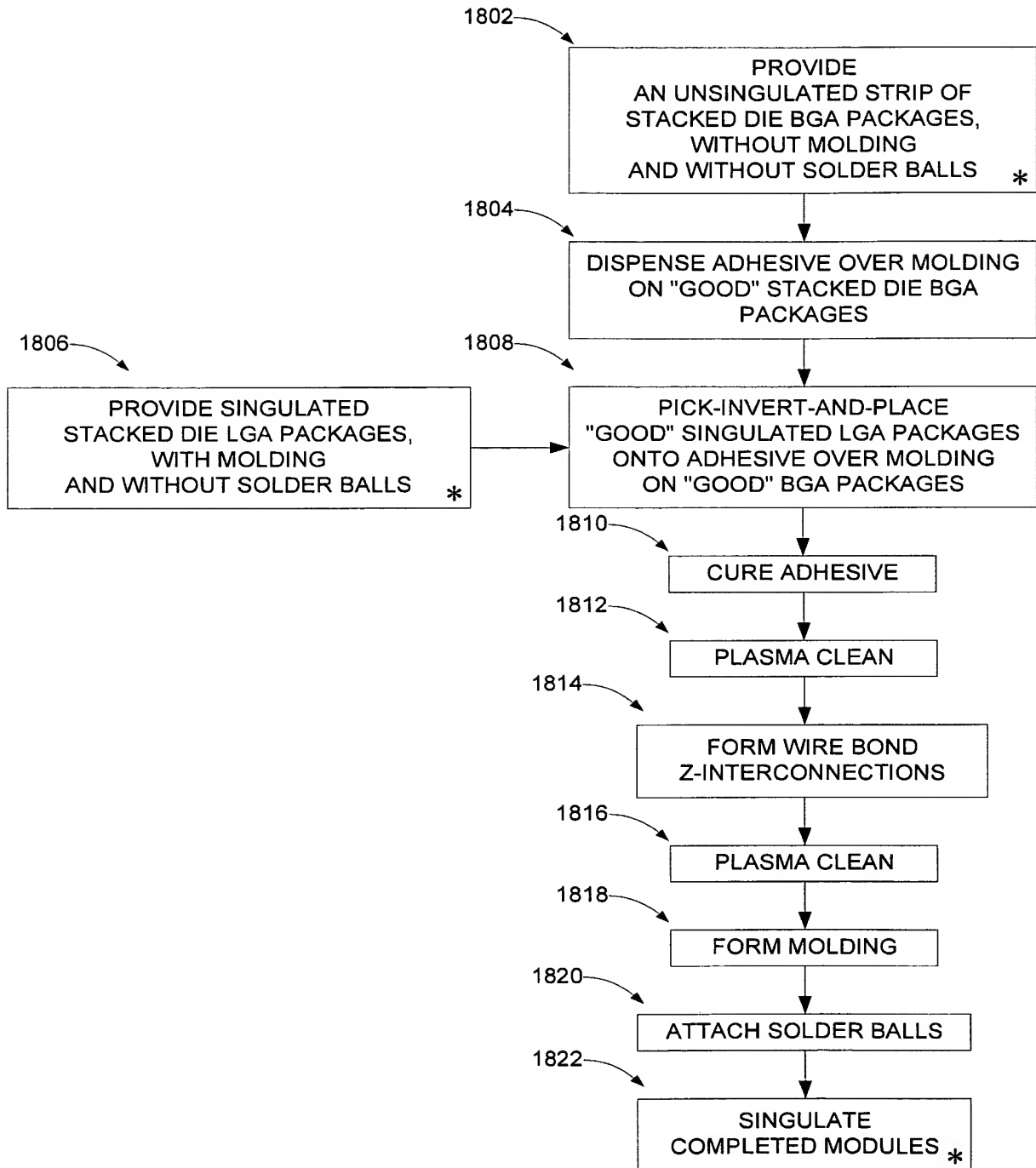


Fig. 18